Salahuddin Raju

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/5502813/publications.pdf

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17	665	1478505 6	1281871 11
papers	citations	h-index	g-index

17	17	17	1232
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Low-Loss RF Passive Elements by Top-Metal Air-Gap Technology. , 2022, , .		1
2	Air-Gap Technology With a Large Void-Fraction for Global Interconnect Delay Reduction. IEEE Transactions on Electron Devices, 2021, 68, 5078-5084.	3.0	5
3	Simultaneous Magnetic Resonance Wireless Power and High-Speed Data Transfer System With Cascaded Equalizer for Variable Channel Compensation. IEEE Transactions on Power Electronics, 2019, 34, 11594-11604.	7.9	13
4	Interconnect Technology With h-BN-Capped Air-Gaps. IEEE Electron Device Letters, 2019, 40, 1876-1879.	3.9	6
5	Prototyping of Terahertz Metasurface by One-Step Lithographically Defined Templating. IEEE Photonics Technology Letters, 2018, 30, 971-974.	2.5	2
6	Selfâ€Driven Metalâ€“Semiconductorâ€“Metal WSe₂ Photodetector with Asymmetric Contact Geometries. Advanced Functional Materials, 2018, 28, 1802954.	14.9	131
7	On-Demand Band-Rejected Wideband Antenna Based on Peelable Resonator Membrane. IEEE Antennas and Wireless Propagation Letters, 2018, 17, 2339-2343.	4.0	1
8	Low Power Phase Change Memory With Vertical Carbon Nanotube Electrode. IEEE Journal of the Electron Devices Society, 2017, 5, 362-366.	2.1	5
9	Ultra-Low-k interlayer dielectric for post-moore CMOS interconnect. , 2017, , .		0
10	Ultralow- k Dielectric With Nanotubes Assisted Vertically Aligned Cylindrical Pores. IEEE Electron Device Letters, 2016, 37, 1493-1496.	3.9	5
11	Carbon nanotube enhanced CMOS interconnect. , 2016, , .		1
12	Carrier Type Control of WSe₂ Fieldâ€Effect Transistors by Thickness Modulation and MoO₃ Layer Doping. Advanced Functional Materials, 2016, 26, 4223-4230.	14.9	167
13	Efficient on-chip wireless power transmission (invited paper). , 2015, , .		0
14	Modeling of on-chip wireless power transmission system (invited paper). , 2015, , .		0
15	Efficient wireless power transmission technology based on above-CMOS integrated (ACI) high quality inductors. , 2014, , .		8
16	Modeling of Mutual Coupling Between Planar Inductors in Wireless Power Applications. IEEE Transactions on Power Electronics, 2014, 29, 481-490.	7.9	276
17	Silicon-Embedded Receiving Coil for High-Efficiency Wireless Power Transfer to Implantable Biomedical ICs. IEEE Electron Device Letters, 2013, 34, 9-11.	3.9	44